



JPW
PATENT
8007-1116

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Takashi SUEYOSHI et al.

Conf. 1846

Application No. 10/594,221

Group 1712

Filed September 25, 2006

Examiner unknown

SILICON-CONTAINING CURING COMPOSITION AND HEAT CURED
PRODUCT THEREOF

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

February 15, 2008

Sir:

In compliance with Rules 1.97 and 1.98, and in fulfillment of the duty of disclosure under Rule 1.56, the cited document is made of record on the enclosed PTO Form-1449.

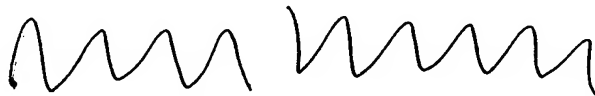
A concise explanation of the relevance of this item is that this reference was cited by the State Intellectual Property Office of China in the corresponding Chinese Application Serial No. 200580007961.4. A copy of the Chinese Official Action in which it was cited is attached hereto. **An English translation is also attached hereto.**

The attached English abstract is from the PCT application corresponding to the cited reference.

Under the provisions of 37 CFR 1.97(e), the undersigned hereby certifies that each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign Patent Office in a counterpart foreign application not more than three months prior to the filing of this Statement.

Respectfully submitted,

YOUNG & THOMPSON



Robert J. Patch, Reg. No. 17,355
745 South 23rd Street
Arlington, VA 22202
Telephone (703) 521-2297
Telefax (703) 685-0573
(703) 979-4709

RJP/fb